MC14516B

Binary Up/Down Counter

The MC14516B synchronous up/down binary counter is constructed with MOS P−channel and N−channel enhancement mode devices in a monolithic structure.

This counter can be preset by applying the desired value, in binary, to the Preset inputs (P0, P1, P2, P3) and then bringing the Preset Enable (PE) high. The direction of counting is controlled by applying a high (for up counting) or a low (for down counting) to the UP/DOWN input. The state of the counter changes on the positive transition of the clock input.

Cascading can be accomplished by connecting the $\overline{\text{Carry Out}}$ to the $\overline{\text{Carry In}}$ of the next stage while clocking each counter in parallel. The outputs (Q0, Q1, Q2, Q3) can be reset to a low state by applying a high to the reset (R) pin.

This CMOS counter finds primary use in up/down and difference counting. Other applications include: (1) Frequency synthesizer applications where low power dissipation and/or high noise immunity is desired, (2) Analog−to−Digital and Digital−to−Analog conversions, and (3) Magnitude and sign generation.

Features

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Speed
- Logic Edge−Clocked Design — Count Occurs on Positive Going Edge of Clock
- Single Pin Reset
- Asynchronous Preset Enable Operation
- Capable of Driving Two Low−Power TTL Loads or One Low−Power Schottky Load Over the Rated Temperature Range
- Pb−Free Packages are Available*

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	−0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V_{in}, V_{out}	−0.5 to V_{DD} + 0.5	V
Input or Output Current (DC or Transient) per Pin	I_{in}, I_{out}	±10	mA
Power Dissipation, per Package (Note 1)	P_D	500	mW
Ambient Temperature Range	T_A	−55 to +125	°C
Storage Temperature Range	T_{stg}	−65 to +150	°C
Lead Temperature (8−Second Soldering)	T_L	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic “P and D/DW” Packages: – 7.0 mW/°C From 65°C To 125°C

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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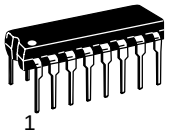
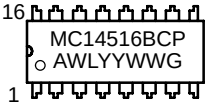
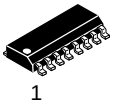
MARKING DIAGRAMS

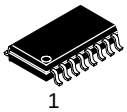


PDIP−16
P SUFFIX
CASE 648

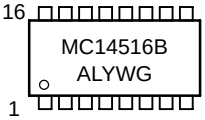




SOIC−16
D SUFFIX
CASE 751B



SOEIAJ−16
F SUFFIX
CASE 966



A	= Assembly Location
WL, L	= Wafer Lot
YY, Y	= Year
WW, W	= Work Week
G	= Pb−Free Package

ORDERING INFORMATION

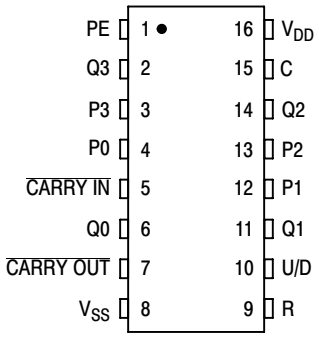
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high−impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \le (V_{in}$ or $V_{out}) \le V_{DD}$.

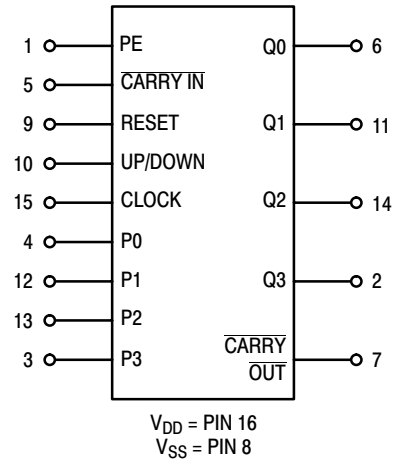
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

Publication Order Number:
MC14516B/D

PIN ASSIGNMENT



BLOCK DIAGRAM



TRUTH TABLE

Carry In	Up/Down	Preset Enable	Reset	Clock	Action
1	X	0	0	X	No Count
0	1	0	0	⎍	Count Up
0	0	0	0	⎍	Count Down
X	X	1	0	X	Preset
X	X	X	1	X	Reset

X = Don't Care

NOTE: When counting up, the $\overline{\text{Carry Out}}$ signal is normally high and is low only when Q0 through Q3 are high and $\overline{\text{Carry In}}$ is low. When counting down, $\overline{\text{Carry Out}}$ is low only when Q0 through Q3 and $\overline{\text{Carry In}}$ are low.

ORDERING INFORMATION

Device	Package	Shipping†
MC14516BCP	PDIP−16	25 Units / Rail
MC14516BCPG	PDIP−16 (Pb−Free)	
MC14516BD	SOIC−16	48 Units / Rail
MC14516BDG	SOIC−16 (Pb−Free)	
MC14516BDR2	SOIC−16	2500 / Tape & Reel
MC14516BDR2G	SOIC−16 (Pb−Free)	
MC14516BF	SOEIAJ−16	50 Units / Rail
MC14516BFG	SOEIAJ−16 (Pb−Free)	
MC14516BFEL	SOEIAJ−16	2000 / Tape & Reel
MC14516BFELG	SOEIAJ−16 (Pb−Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	– 55°C Min	– 55°C Max	25°C Min	25°C Typ (Note 2)	25°C Max	125°C Min	125°C Max	Unit
Output Voltage “0” Level V_{in} = V_{DD} or 0	V_{OL}	5.0 10 15	– – –	0.05 0.05 0.05	– – –	0 0 0	0.05 0.05 0.05	– – –	0.05 0.05 0.05	Vdc
“1” Level V_{in} = 0 or V_{DD}	V_{OH}	5.0 10 15	4.95 9.95 14.95	– – –	4.95 9.95 14.95	5.0 10 15	– – –	4.95 9.95 14.95	– – –	Vdc
Input Voltage “0” Level (V_O = 4.5 or 0.5 Vdc) (V_O = 9.0 or 1.0 Vdc) (V_O = 13.5 or 1.5 Vdc)	V_{IL}	5.0 10 15	– – –	1.5 3.0 4.0	– – –	2.25 4.50 6.75	1.5 3.0 4.0	– – –	1.5 3.0 4.0	Vdc
“1” Level (V_O = 0.5 or 4.5 Vdc) (V_O = 1.0 or 9.0 Vdc) (V_O = 1.5 or 13.5 Vdc)	V_{IH}	5.0 10 15	3.5 7.0 11	– – –	3.5 7.0 11	2.75 5.50 8.25	– – –	3.5 7.0 11	– – –	Vdc
Output Drive Current (V_{OH} = 2.5 Vdc) Source (V_{OH} = 4.6 Vdc) (V_{OH} = 9.5 Vdc) (V_{OH} = 13.5 Vdc)	I_{OH}	5.0 5.0 10 15	– 3.0 – 0.64 – 1.6 – 4.2	– – – –	– 2.4 – 0.51 – 1.3 – 3.4	– 4.2 – 0.88 – 2.25 – 8.8	– – – –	– 1.7 – 0.36 – 0.9 – 2.4	– – – –	mAdc
(V_{OL} = 0.4 Vdc) Sink (V_{OL} = 0.5 Vdc) (V_{OL} = 1.5 Vdc)	I_{OL}	5.0 10 15	0.64 1.6 4.2	– – –	0.51 1.3 3.4	0.88 2.25 8.8	– – –	0.36 0.9 2.4	– – –	mAdc
Input Current	I_{in}	15	–	± 0.1	–	±0.00001	± 0.1	–	± 1.0	μAdc
Input Capacitance (V_{in} = 0)	C_{in}	–	–	–	–	5.0	7.5	–	–	pF
Quiescent Current (Per Package)	I_{DD}	5.0 10 15	– – –	5.0 10 20	– – –	0.005 0.010 0.015	5.0 10 20	– – –	150 300 600	μAdc
Total Supply Current (Note 3, 4) (Dynamic plus Quiescent, Per Package) (C_L = 50 pF on all outputs, all buffers switching)	I_T	5.0 10 15	I_T = (0.58 μA/kHz) f + I_{DD} I_T = (1.20 μA/kHz) f + I_{DD} I_T = (1.70 μA/kHz) f + I_{DD}							μAdc

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.
3. The formulas given are for the typical characteristics only at 25°C.
4. To calculate total supply current at loads other than 50 pF: $I_T(C_L) = I_T(50\ pF) + (C_L - 50)$ Vfk where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.001.

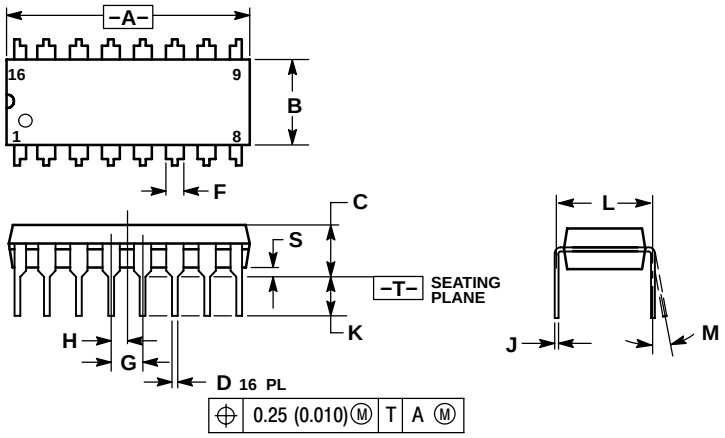
SWITCHING CHARACTERISTICS (Note 5) (C_L = 50 pF, T_A = 25°C)

Characteristic	Symbol	V_{DD}	All Types			Unit
			Min	Typ (Note 6)	Max	
Output Rise and Fall Time t_{TLH}, t_{THL} = (1.5 ns/pF) C_L + 25 ns t_{TLH}, t_{THL} = (0.75 ns/pF) C_L + 12.5 ns t_{TLH}, t_{THL} = (0.55 ns/pF) C_L + 9.5 ns	t_{TLH}, t_{THL}	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 230 ns t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 97 ns t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 75 ns	t_{PLH}, t_{PHL}	5.0 10 15	– – –	315 130 100	630 260 200	ns
Clock to $\overline{\text{Carry Out}}$ t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 230 ns t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 97 ns t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 75 ns	t_{PLH}, t_{PHL}	5.0 10 15	– – –	315 130 100	630 260 200	ns
$\overline{\text{Carry In}}$ to $\overline{\text{Carry Out}}$ t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 230 ns t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 97 ns t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 75 ns	t_{PLH}, t_{PHL}	5.0 10 15	– – –	180 80 60	360 160 120	ns
Preset or Reset to Q t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 230 ns t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 97 ns t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 75 ns	t_{PLH}, t_{PHL}	5.0 10 15	– – –	315 130 100	630 360 200	ns
Preset or Reset to $\overline{\text{Carry Out}}$ t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 465 ns t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 192 ns t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 125 ns	t_{PLH}, t_{PHL}	5.0 10 15	– – –	550 225 150	1100 450 300	ns
Reset Pulse Width	t_w	5.0 10 15	380 200 160	190 100 80	– – –	ns
Clock Pulse Width	t_{WH}	5.0 10 15	350 170 140	200 100 75	– – –	ns
Clock Pulse Frequency	f_{cl}	5.0 10 15	– – –	3.0 6.0 8.0	1.5 3.0 4.0	MHz
Preset or Reset Removal Time The Preset or Reset signal must be low prior to a positive−going transition of the clock.	t_{rem}	5.0 10 15	650 230 180	325 115 90	– –	ns
Clock Rise and Fall Time	t_{TLH}, t_{THL}	5.0 10 15	– – –	– – –	15 5 4	μs
Setup Time $\overline{\text{Carry In}}$ to Clock	t_{su}	5.0 10 15	260 120 100	130 60 50	– – –	ns
Hold Time Clock to $\overline{\text{Carry In}}$	t_h	5.0 10 15	0 20 20	– 60 – 20 0	– – –	ns
Setup Time Up/Down to Clock	t_{su}	5.0 10 15	500 200 150	250 100 75	– – –	ns
Hold Time Clock to Up/Down	t_h	5.0 10 15	– 70 – 10 0	– 160 – 60 – 40	– – –	ns
Setup Time Pn to PE	t_{su}	5.0 10 15	– 40 – 30 – 25	– 120 – 70 – 50	– – –	ns
Hold Time PE to Pn	t_h	5.0 10 15	480 420 420	240 210 210	– – –	ns
Preset Enable Pulse Width	t_{WH}	5.0 10 15	200 100 80	100 50 40	– – –	ns

5. The formulas given are for the typical characteristics only at 25°C.
6. Data labelled “Typ” is not to be used for design purposes but is intended as an Indication of the IC’s potential performance.

PACKAGE DIMENSIONS

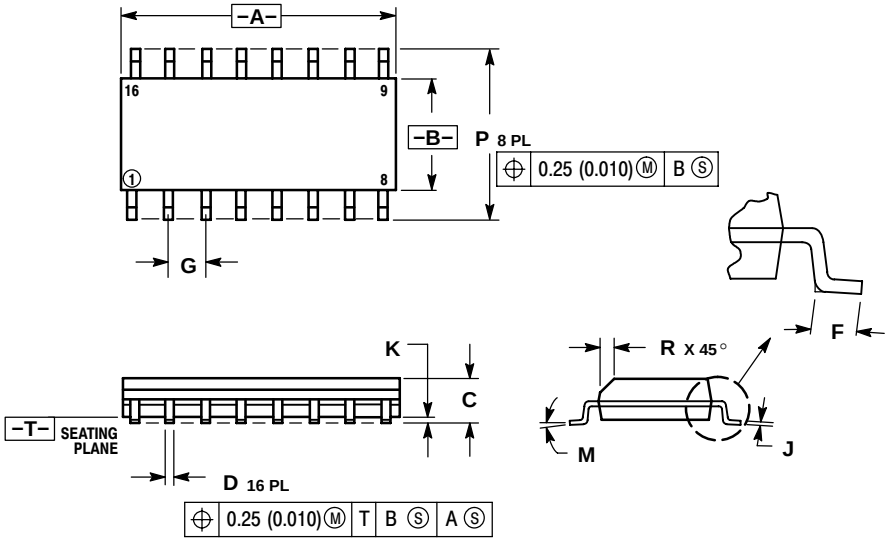
PDIP−16
CASE 648−08
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

SOIC−16
CASE 751B−05
ISSUE J



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019